THALES

www.thalesgroup.com/microelectronics

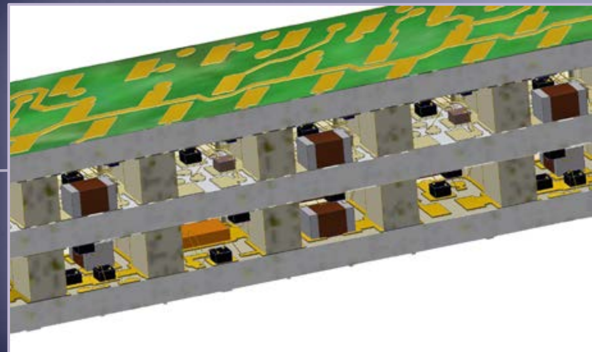
CONSULT US TO GET YOUR OWN CUSTOM MODULE!

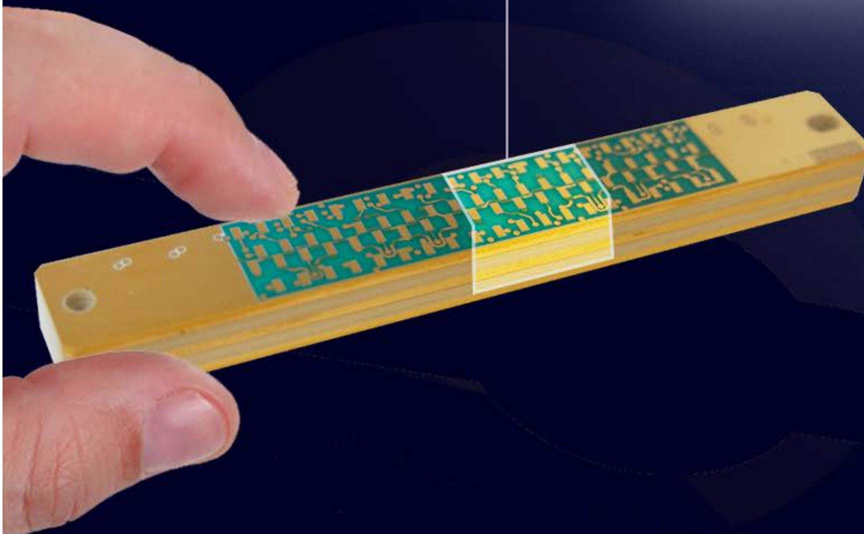
FUNCTIONAL DESCRIPTION

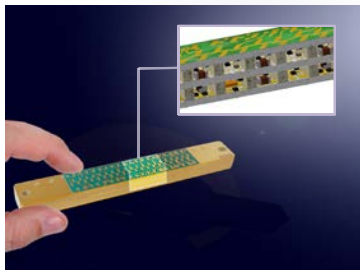
This 3D-Organic package makes it possible to integrate functions covering a wide range of frequencies from DC to microwave.
With its custom sizing, shaping and terminations, Thales provides a fully tailored packaging solution up to your requirements.

Thales Microelectronics

Ultra high-density 3D-organic packaging







Thales Microelectronics

High-density 3D-organic packaging

MAIN FEATURES

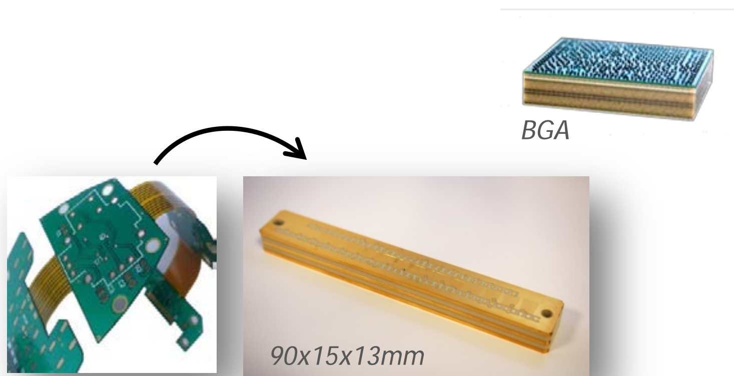
- Miniaturized modular function
- Multi-cavity structure
- 6-side shielded cavity capability
- Hi-reliability packaging
- Air-tight packaging
- Thermal management

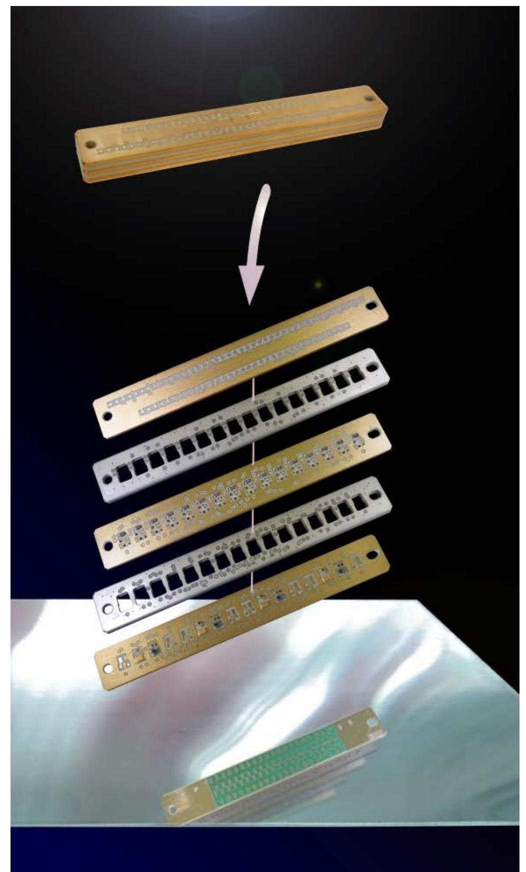
ASSETS

- Custom terminations
- Custom packaging sizing and shaping
- 167 components in 20cm3
- Size reduced by factor 10
- Signal length reduced by factor 5

TECHNOLOGIES

- Conventional process assembly: SMT,...
- Optional lead-free process
- Matched thermal expansion coefficients between package and mother board
- Terminations: BGA, LGA, leads, connectors,...





ENVIRONMENTAL CAPABILITIES

- Temperature range: -55°C to +125°C
- Qualification level: MIL and AERO

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THALES
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